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First edition
2007-05

Workmanship requirements for soldered electronic assemblies –

Part 5: Rework, modification and repair of soldered electronic assemblies

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CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	8
3 Terminology	9
3.1 Terms and definitions	9
3.2 Abbreviations	9
4 Classification of rework activities	10
4.1 Pre-soldering rework	10
4.2 Post-soldering rework.....	10
4.3 Essential prerequisites for successful and reliable rework	10
5 Pre-soldering rework	11
5.1 General	11
5.2 Reworking solder paste and non-conducting adhesive deposits.....	11
5.2.1 General	11
5.2.2 General misalignment or smudging of deposits.....	11
5.2.3 Local misalignment or smudging of deposit.....	11
5.2.4 General paste or adhesive quantity incorrect	12
5.2.5 Local paste or adhesive quantity incorrect.....	12
5.3 Reworking placed components	12
5.3.1 General overall component misalignment	12
5.3.2 Local component misalignment.....	12
5.4 Realigning components after curing thermoplastic adhesive	12
5.5 Realigning components after curing thermosetting adhesive.....	12
6 Factors affecting post-soldering rework	13
6.1 Component marking and unmarked components	13
6.2 Reuse of removed components	13
6.3 Sensitive components	13
6.4 Printed board layout design and space constraints	14
6.5 Heat-sink effects.....	14
6.6 Printed board material type	14
6.7 Solder resist material and aperture size	15
6.8 Reworking individual fine pitch device leads	16
6.9 Reworking grid arrays	16
7 Preparation for post-soldering rework and repair	17
7.1 Electrostatic precautions	17
7.2 Avoiding exposure of components to contaminants.....	17
7.3 Removal of conformal coating	17
7.4 Unsuitable components	18
7.5 Cleaning prior to rework	18
7.6 Protecting adjacent sensitive components	18
7.7 Baking of assemblies prior to component replacement	18
7.8 Preheating large multilayer boards	18
7.9 Preheating replacement sensitive components	18
8 Post-soldering rework.....	19
8.1 General.....	19

8.2	Component realignment (tweaking)	19
8.3	Component removal	19
8.4	Removal of adjacent components	19
8.5	Reuse of components	19
8.6	Addition of flux and solder	20
8.7	Topping-up	20
8.8	Removal of excess solder from joints	21
8.9	Preparation of lands before component replacement	21
8.10	Component replacement	22
8.11	Cleaning (if required)	22
8.12	Visual inspection and electrical testing	22
8.13	Checking thermal integrity of solder joints	22
8.14	Replacement of local conformal coating (if required)	22
9	Selection of rework equipment, tools and methods	22
9.1	General	22
9.2	Matching rework equipment to component and printed-board prerequisites	23
9.2.1	General	23
9.2.2	Selection based on component types on the printed board	24
9.2.3	Selection based on printed-board laminate material type	24
9.2.4	Selection based on assembly structure and soldering processes	24
10	Manual rework tools and methods	26
10.1	General	26
10.2	Miniature conventional (stored energy) soldering irons	26
10.3	Directly heated soldering irons	27
10.4	Hot air/gas pencils	28
10.5	Heated tweezers	28
10.6	Soldering irons with special tips	29
11	Mechanized and programmable rework machines	29
11.1	General	29
11.2	Hot air rework machines	29
11.3	Focused infrared (IR) equipment	30
11.4	Thermode (heated electrode) equipment	31
11.5	Laser equipment for de-soldering	32
12	Ancillary tools and equipment	33
12.1	Conventional soldering irons	33
12.2	Hotplates	33
12.3	Pneumatic dispensers	33
12.4	De-soldering tools, as used for through-hole assemblies	34
12.5	Tweezers and vacuum pencils	34
12.6	Solder pots	34
12.7	Copper braid	34
13	Rework recording procedures	34
13.1	General	34
13.2	Anomaly charts	34
13.3	Travelling documents	35
13.4	Rework status	36
14	Training of operators and inspectors	36
15	Field repair	37

Bibliography.....	38
Figure 1 – Typical in-process modification, rework or repair activities	7
Figure 2 – Gang mounting no solder mask between lands.....	15
Figure 3 – Conductor between lands on small pitch	15
Figure 4 – Optional solder-mask design for multiple termination component attachment.....	16
Figure 5 – SOIC repair procedure example	23
Figure 6 – Comparing hot air/gas and infrared rework processes	26
Figure 7 – Miniature conventional soldering iron	27
Figure 8 – Hot air solder system	30
Figure 9 – Heated thermode reflow soldering.....	31
Figure 10 – Automated laser reflow equipment	33
Table 1 – Recommended tools for different component types	25
Table 2 – Electrical and electronic assembly defects	35

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**WORKMANSHIP REQUIREMENTS FOR
SOLDERED ELECTRONIC ASSEMBLIES –****Part 5: Rework, modification and repair of
soldered electronic assemblies**

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International Standard IEC 61192-5 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/652/FDIS	91/686/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61192 series, under the general title *Workmanship requirements for soldered electronic assemblies*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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WORKMANSHIP REQUIREMENTS FOR SOLDERED ELECTRONIC ASSEMBLIES –

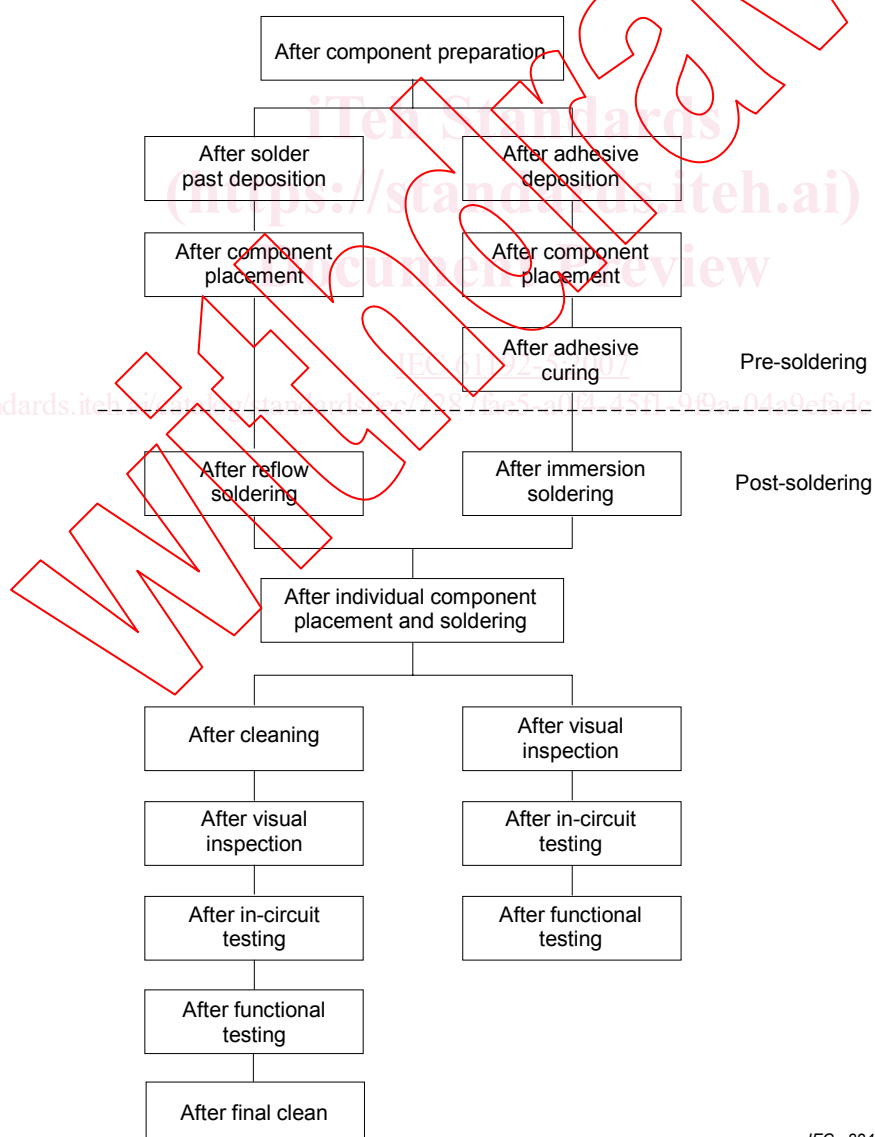
Part 5: Rework, modification and repair of soldered electronic assemblies

1 Scope

This part of IEC 61192 provides information and requirements that are applicable to modification, rework and repair procedures for soldered electronic assemblies. It is applicable to specific processes used to manufacture soldered electronic assemblies where components are attached to printed boards and to the relevant parts of resulting products. The standard is also applicable to activities that can form part of the work in assembling mixed technology products.

This part of IEC 61192 also contains guidance on design matters where they have relevance to rework.

NOTE Typical in-process surface-mount rework activities to which this standard applies are shown in Figure 1.



IEC 824/07

Figure 1 – Typical in-process modification, rework or repair activities

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61190-1-1, *Attachment materials for electronic assembly – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-2, *Attachment materials for electronic assembly – Part 1-2: Requirements for solder paste for high-quality interconnections in electronics assembly*

IEC 61190-1-3, *Attachment materials for electronics assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

IEC 61191-1:1998, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IEC 61191-2:1998, *Printed board assemblies – Part 2: Sectional specification – Requirements for surface mount soldered assemblies*

IEC 61191-3, *Printed board assemblies – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies*

IEC 61191-4, *Printed board assemblies – Part 4: Sectional specification – Requirements for terminal soldered assemblies*

IEC 61192-1, *Workmanship requirements for soldered electronic assemblies – Part 1: General*

IEC 61192-2, *Workmanship requirements for soldered electronic assemblies – Part 2: Surface-mount assemblies*

IEC 61192-3, *Workmanship requirements for soldered electronic assemblies – Part 3: Through-hole mount assemblies*

IEC 61192-4, *Workmanship requirements for soldered electronic assemblies – Part 4: Terminal assemblies*

IEC 61193-1, *Quality assessment systems – Part 1: Registration and analysis of defects on printed board assemblies*

IEC 61249 (all parts), *Materials for printed boards and other interconnecting structures*

3 Terminology

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194, some of which (marked with an asterisk) are repeated below for convenience, as well as the following, apply.

3.1.1

rework*

act of reprocessing non-complying articles, through the use of original or alternate equivalent processing, in a manner that assures compliance of the article with applicable drawings or specifications

3.1.2

repair*

act of restoring the functional capability of a defective article in a manner that precludes compliance of the article with applicable drawings or specifications

3.1.3

modification*

revision of the functional capability of a product in order to satisfy new acceptance criteria

3.1.4

anomaly chart

copy of an assembly drawing (or of an actual printed board assembly) that is used to record the location of faults or process indicators used for process improvement analysis

3.1.5

added component

electronic component that is mounted on a printed board by soldering or other attachment methods

3.1.6

embedded component

electronic component that is an integral part of a printed board, for example, embedded resistors, capacitive layers, printed inductors

3.2 Abbreviations

The following abbreviations are commonly used in relation to printed board assemblies. Not all of them are used in the text. Some are included for information only.

ASIC	application-specific integrated circuit
BGA	ball grid array
CLCC	ceramic leaded chip carrier
CLLCC	ceramic leadless chip carrier
LCCC	leadless ceramic chip carrier
LED	light-emitting diode
MELF	metal electrode face-bonded component
PLCC	plastic leaded chip carrier
PTFE	polytetrafluoroethylene
QFP	plastic quad flat package

RMA	rosin, mildly active
SMD	surface-mounted device
SMT	surface-mount technology
SO	small outline
SOD	small outline diode
SOIC	small outline integrated circuit
SOT	small outline transistor
TSOP	plastic thin small outline package

4 Classification of rework activities

4.1 Pre-soldering rework

This includes rework following:

- a) component preparation;
- b) deposition of solder (e.g. paste, preform, tinning);
- c) deposition of adhesive;
- d) component placement;
- e) curing of adhesive.

NOTE In the context of this standard, the word "component" includes all added components, printed boards and any components that are manufactured integrally with the printed board.

4.2 Post-soldering rework

Post-soldering rework activities, not necessarily occurring in the order given, include:

- a) preparation prior to rework or repair, for example, removal of conformal coating, preheating, baking, cleaning, removal of adjacent components and parts to enable access;
- b) component realignment;
- c) component removal;
- d) addition of flux and solder to a joint;
- e) removal of excess solder from a joint;
- f) removal of excess solder or adhesive from the printed board prior to remounting a component;
- g) placement and soldering of a replacement component;
- h) post-rework cleaning (if required);
- i) visual, thermal, mechanical and dimensional inspection and electrical test of reworked items.

4.3 Essential prerequisites for successful and reliable rework

The essential prerequisites for successful and reliable rework include the following:

- a) suitable printed-board layout design to allow the preferred tool to be used for each component type;
- b) confirmation of the type of solder used for the interconnection and selection of the appropriate process (tin/lead, lead free, other), and replacement material;
- c) availability of the most efficient tool or equipment for the task plus antistatic protection;